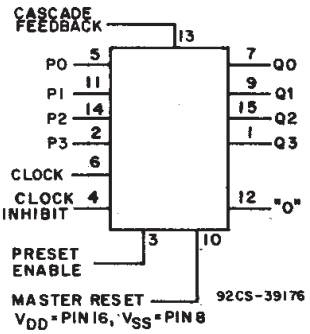
TEXAS INSTRUMENTS
Data sheet acquired from Harris Semiconductor
SCHS079C – Revised October 2003

NOT RECOMMENDED FOR NEW DESIGNS

CD4522B Types

Advance Information/ Preliminary Data



FUNCTIONAL DIAGRAM

CMOS Programmable BCD Divide-by-"N" Counter

High-Voltage Types (20-Volt Rating)

Features:

- *Internally synchronous for high internal and external speeds.*
- *Logic edge-clocked design — increments on positive Clock transition or on negative Clock Inhibit transition.*
- *100% tested for quiescent current at 20-V.*
- *5-V, 10-V, and 15-V parametric ratings.*
- *Standard symmetrical output characteristics.*
- *Maximum input current of 1 μA at 18 V over full package-temperature range: 100 nA at 18 V and 25° C.*
- *Meets all requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."*

■ CD4522B programmable BCD counter has a decoded "0" state output for divide-by-N applications. In single stage operation the "0" output is tied to the Preset Enable input. The Cascade Feedback allows multiple stage divide-by-N operation without the need for external gating. A HIGH on the Clock Inhibit disables the pulse-counting function. A HIGH on the Master Reset asynchronously resets the divide-by-N operation. The output is presented in BCD format.

The CD4522B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Applications:

- *Frequency synthesizers*
- *Phase-locked loops*
- *Programmable down counters*
- *Programmable frequency dividers*

3 COMMERCIAL CMOS HIGH VOLTAGE ICs

MAXIMUM RATINGS, *Absolute-Maximum Values:*

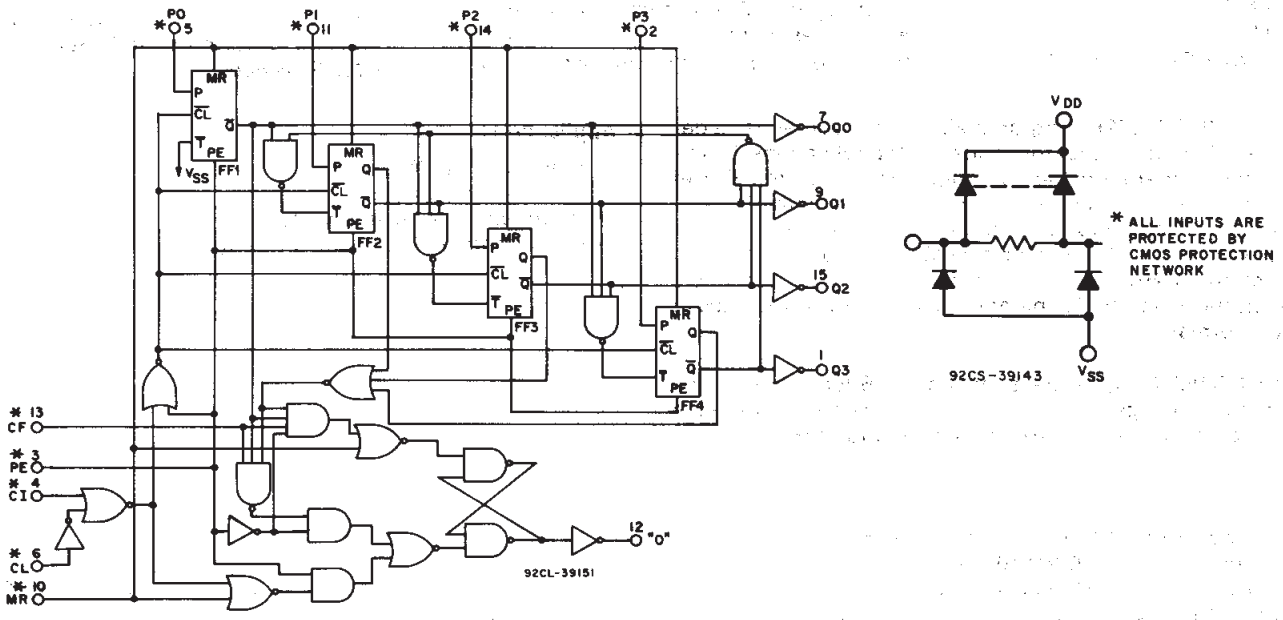
DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

TRUTH TABLES

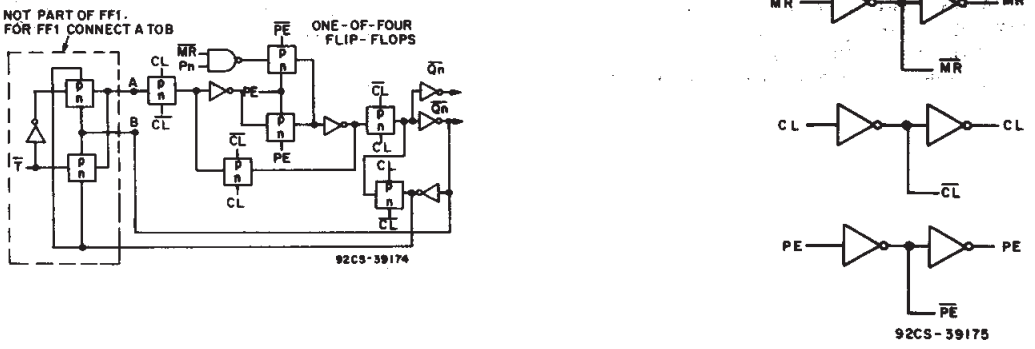
CLOCK	CLOCK INHIBIT	PRESET ENABLE	MASTER RESET	ACTION
0	0	0	0	No Count
⌒	0	0	0	Count Down
X	1	0	0	No Count
1	⌒	0	0	Count Down
X	X	1	0	Preset
X	X	X	1	Reset

X = Don't Care

Count	OUTPUTS			
	Q_0	Q_1	Q_2	Q_3
0	0	0	0	0
1	1	0	0	0
2	0	1	0	0
3	1	1	0	0
4	0	0	1	0
5	1	0	1	0
6	0	1	1	0
7	1	1	1	0
8	0	0	0	1
9	1	0	0	1



a. Basic diagram.



b. Flip-flop detail.

Fig. 1 - Logic diagram for the CD4522B.

RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, except as noted.

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	V_{DD} (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For T_A = Full Package-Temperature Range		3	18	V
Pulse Width:				
Clock, $tw_{(CC)}$	5	250	—	ns
	10	100	—	
	15	80	—	
Preset Enable, $tw_{(CC)}$	5	250	—	ns
	10	100	—	
	15	80	—	
Master Reset, $tw_{(MR)}$	5	350	—	ns
	10	250	—	
	15	200	—	
Clock Frequency, f_{CL}	5	—	1.5	MHz
	10	—	3.0	
	15	—	4.0	
Clock Rise and Fall Time t_{rCL}, t_{fCL}	5	—	15	μs
	10	—	15	
	15	—	15	
Preset Enable Set-up Time, t_{su}	5	0	—	ns
	10	0	—	
	15	0	—	
Preset Enable Hold Time, t_h	5	75	—	ns
	10	25	—	
	15	20	—	
Master Reset Removal Time, t_{rem}	5	130	—	ns
	10	50	—	
	15	30	—	

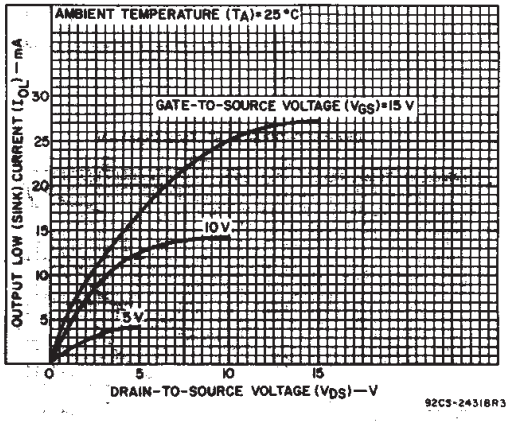


Fig. 2 — Typical output low (sink) current characteristics.

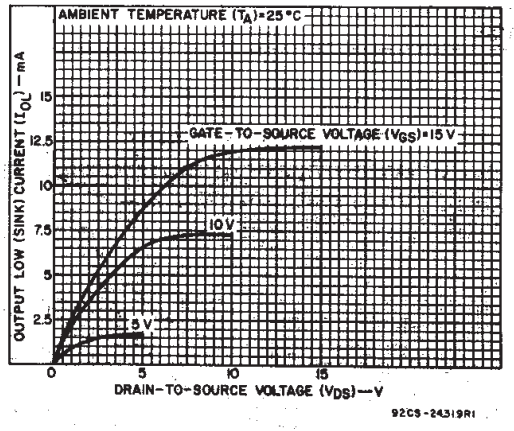


Fig. 3 — Minimum output low (sink) current characteristics.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								+25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	—	0, 5	5	5	5	150	150	—	0.04	5	μA
	—	0, 10	10	10	10	300	300	—	0.04	10	
	—	0, 15	15	20	20	600	600	—	0.04	20	
	—	0, 20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I_{OL} Min.	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I_{OH} Min.	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	
	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V_{OL} Max.	—	0, 5	5	0.05				—	0	0.05	V
	—	0, 10	10	0.05				—	0	0.05	
	—	0, 15	15	0.05				—	0	0.05	
Output Voltage: High-Level V_{OH} Min.	—	0, 5	5	4.95				4.95	5	—	
	—	0, 10	10	9.95				9.95	10	—	
	—	0, 15	15	14.95				14.95	15	—	
Input low Voltage, V_{IL} Max.	0.5, 4.5	—	5	1.5				—	—	1.5	
	1, 9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5, 4.5	—	5	3.5				3.5	—	—	
	1, 9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current, I_{IN} Max.	—	0, 18	18	±0.1	±0.1	±1	±1	—	$\pm 10^{-5}$	±0.1	μA

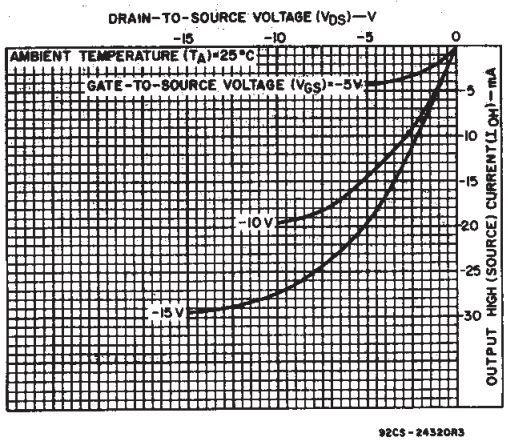


Fig. 4 — Typical output high (source) current characteristics.

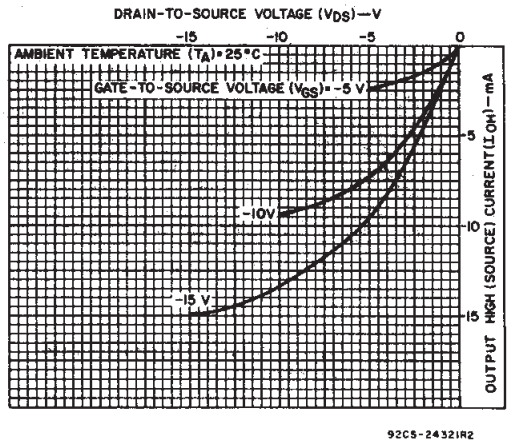


Fig. 5 — Minimum output high (source) current characteristics.

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25°C$, Input t_r, $t_f = 20$ ns, $C_l = 50$ pF, R_L, $= 200$ kΩ

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
	V_{DD} (V)	Min.	Typ.	Max.	
Propagation Delay Time; t_{PHL}, t_{PLH}: Clock to "Q" outputs	5	—	550	1100	ns
	10	—	225	450	
	15	—	160	320	
Clock to "0" output	5	—	420	710	ns
	10	—	160	270	
	15	—	110	190	
Clock inhibit to "Q" outputs	5	—	270	540	ns
	10	—	100	200	
	15	—	70	140	
Master reset to "Q" outputs	5	—	270	540	ns
	10	—	100	200	
	15	—	70	140	
Preset Enable Setup Time, t_{su}	5	—	0	0	ns
	10	—	0	0	
	15	—	0	0	
Preset Enable Hold Time, t_h	5	—	75	150	ns
	10	—	25	50	
	15	—	20	40	
Master Reset Removal Time, t_{rem}	5	—	130	260	ns
	10	—	50	100	
	15	—	30	60	
Transition Time, t_{THL}, t_{TLH}	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Minimum Pulse Width Clock, $t_{W(CL)}$	5	—	125	250	ns
	10	—	50	100	
	15	—	40	80	
Preset Enable, $t_{W(PE)}$	5	—	125	250	ns
	10	—	50	100	
	15	—	40	80	
Master Reset, $t_{W(MR)}$	5	—	175	350	ns
	10	—	125	250	
	15	—	100	200	
Max Clock Freq, f_{CL}	5	—	3	1.5	MHz
	10	—	6	3.0	
	15	—	8	4.0	
Max Clock or Clock Inhibit Rise & Fall Time, t_{TLH}, t_{THL}	5	—	—	15	us
	10	—	—	15	
	15	—	—	15	
Input Capacitance, C_{IN}	Any Input	—	5	7.5	pF

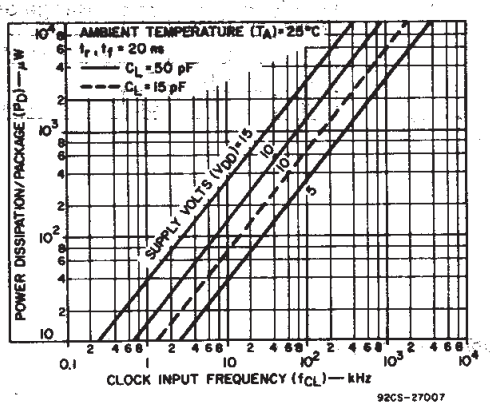
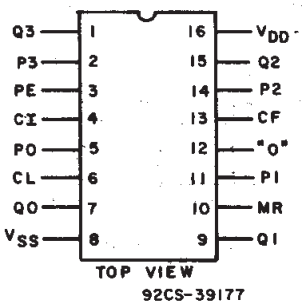


Fig. 6 — Typical dynamic power dissipation vs. frequency.



TERMINAL ASSIGNMENT

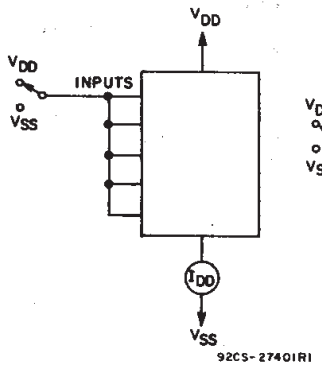


Fig. 7 — Quiescent device current test circuit.

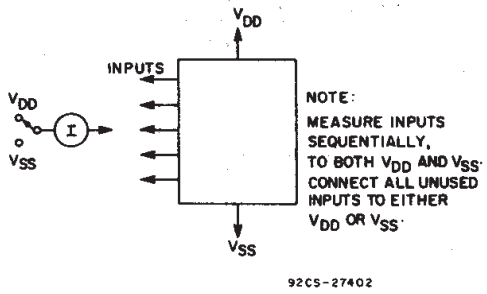


Fig. 8 — Input current test circuit.

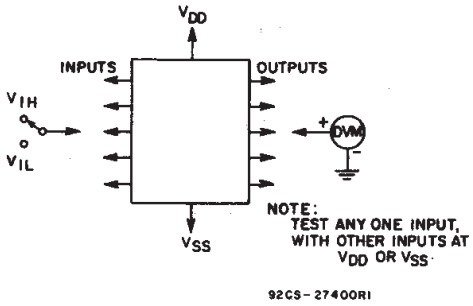
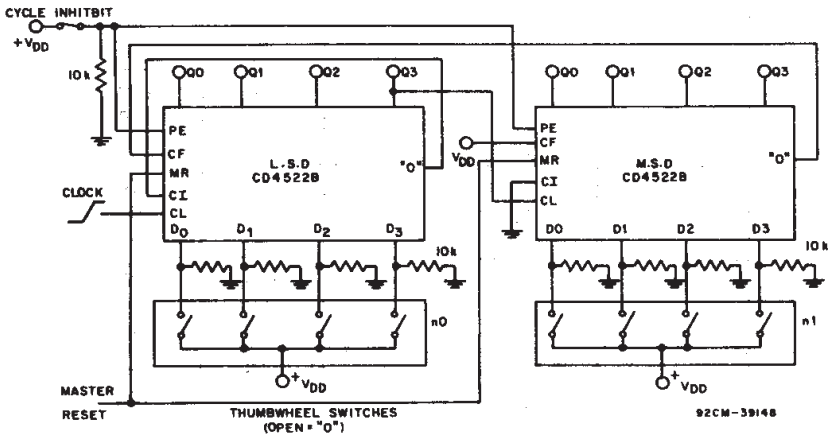


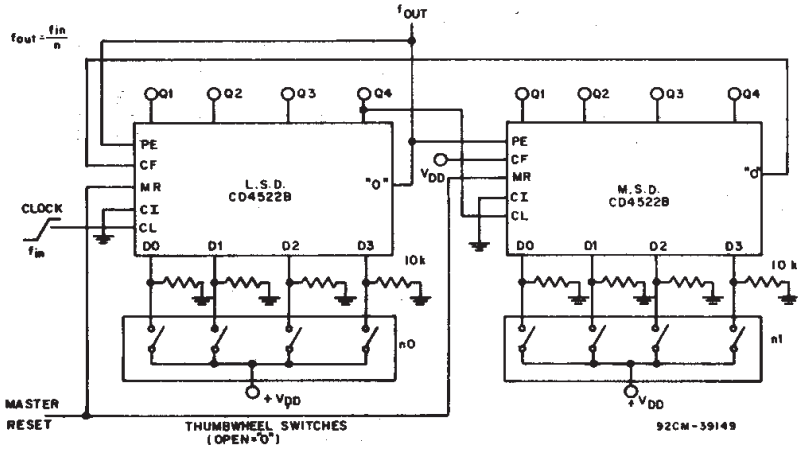
Fig. 9 — Input voltage test circuit.

APPLICATION CIRCUITS



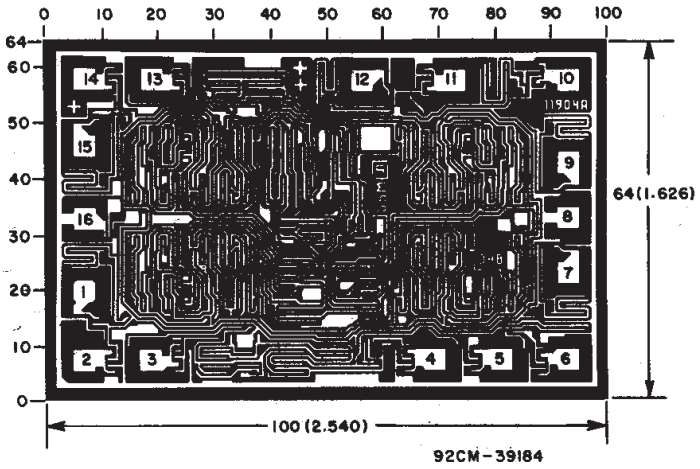
From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0"	N+1	CL	LSD < N < MSD-1

Fig. 10 — 2-Stage Programmable Down Counter (One Cycle)



From		To		Range of N
Stage	Pin	Stage	Pin	
LSD	"0"	All	PE	LSD < N < MSD
N	"0"	N-1	CF	LSD + 1 < N < MSD
N	"0"	N+1	CL	LSD < N < MSD-1

Fig. 11 — 2-Stage Programmable Frequency Divider



Dimensions and pad layout for CD4522BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD4522BE	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4522BE
CD4522BE.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4522BE
CD4522BM	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM
CD4522BM.A	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM
CD4522BMT	Active	Production	SOIC (D) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM
CD4522BMT.A	Active	Production	SOIC (D) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4522BM
CD4522BPW	Active	Production	TSSOP (PW) | 16	90 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B
CD4522BPW.A	Active	Production	TSSOP (PW) | 16	90 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM522B

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

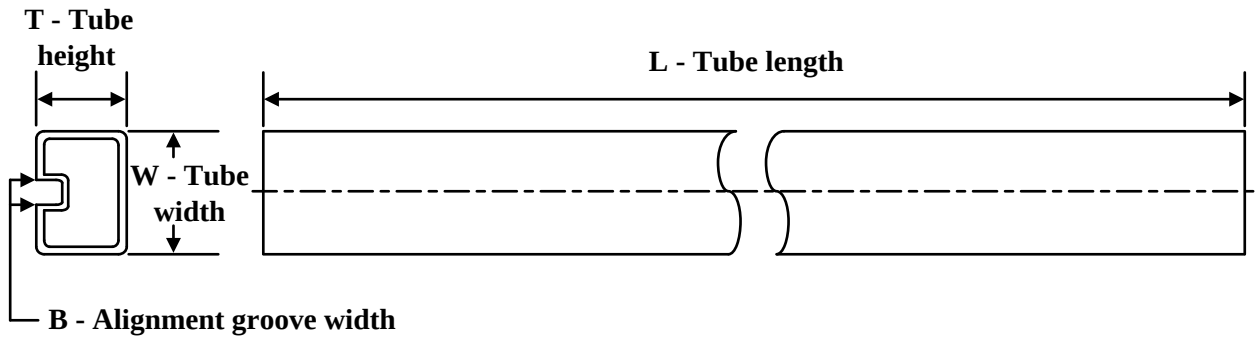
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

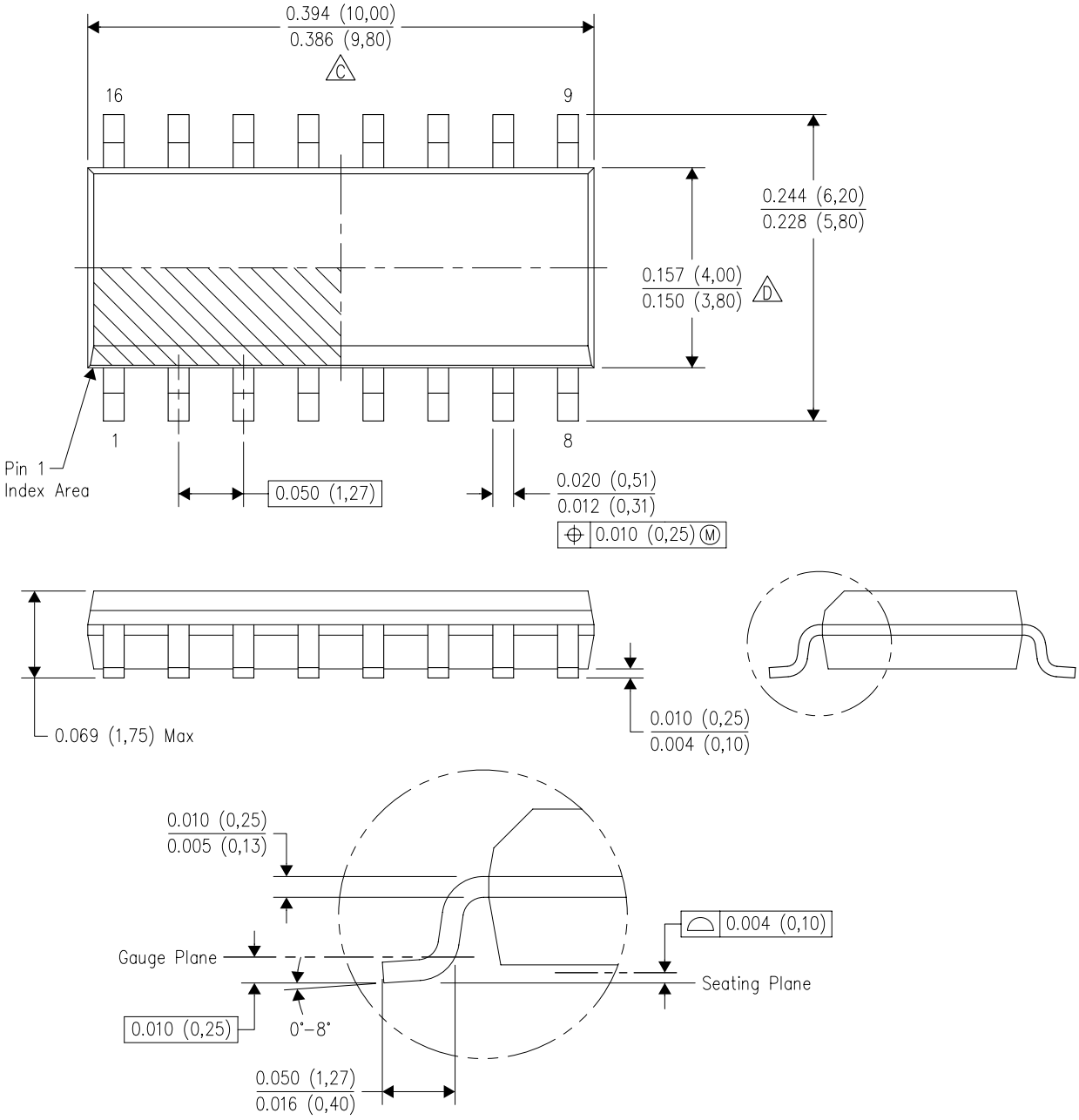
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4522BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4522BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4522BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD4522BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD4522BM	D	SOIC	16	40	507	8	3940	4.32
CD4522BM.A	D	SOIC	16	40	507	8	3940	4.32
CD4522BPW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD4522BPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



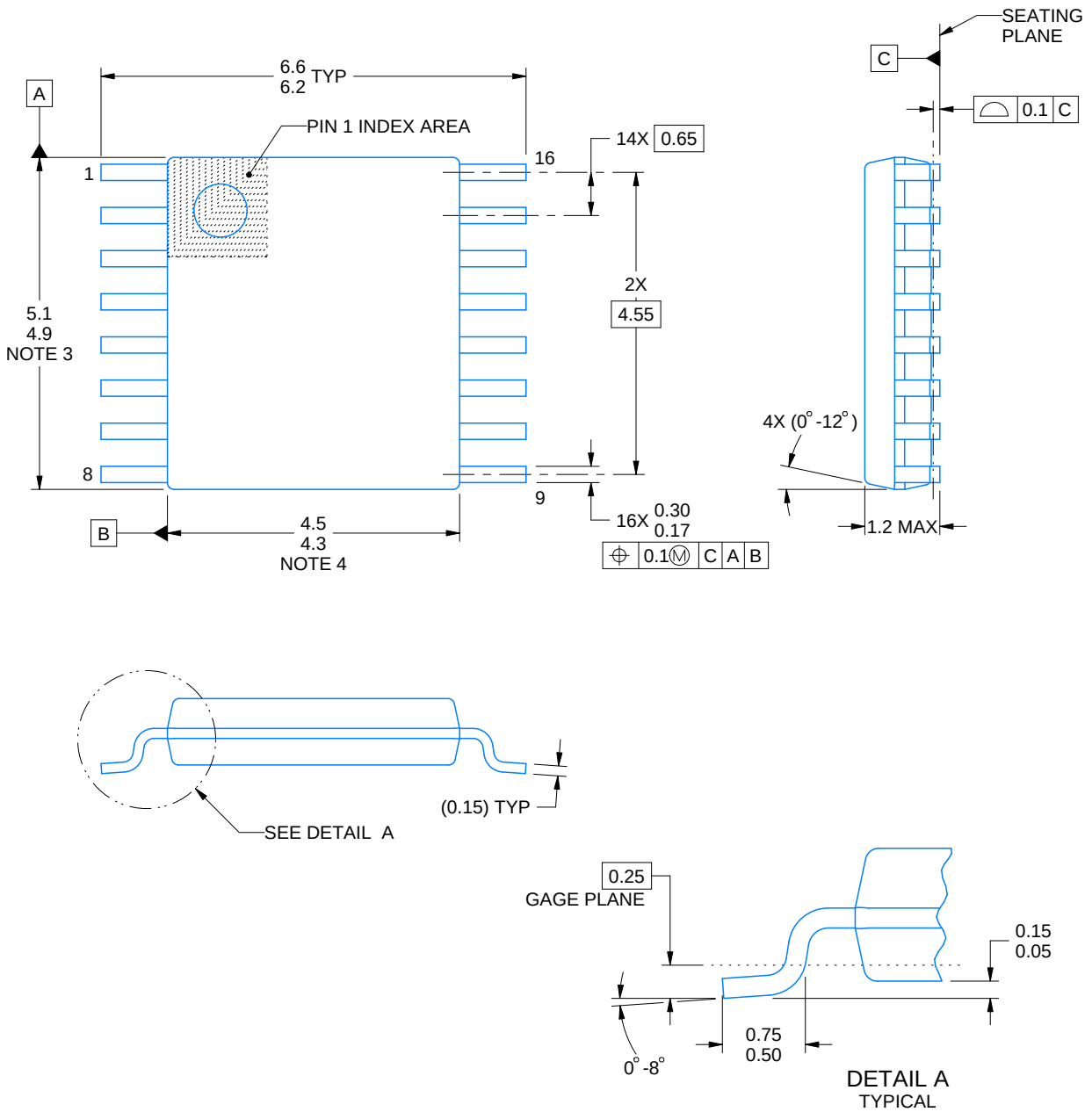
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

PACKAGE OUTLINE

PW0016A

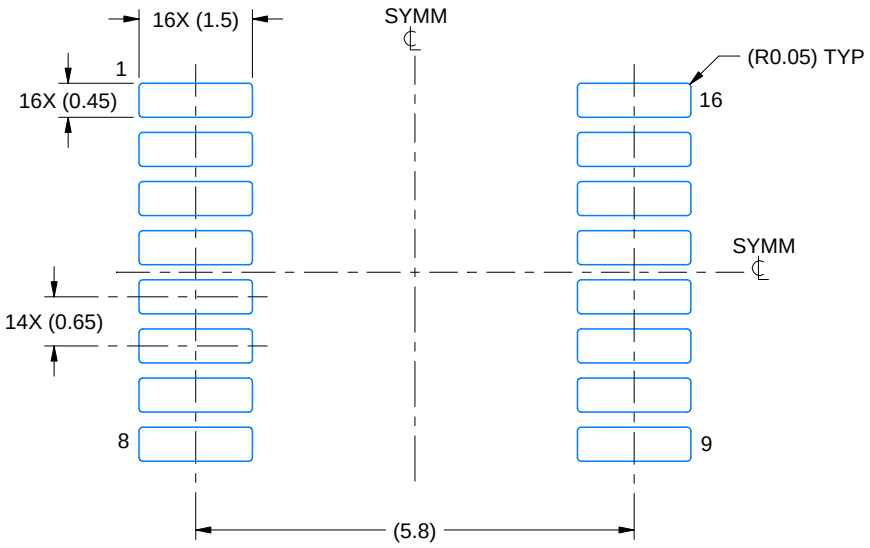
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



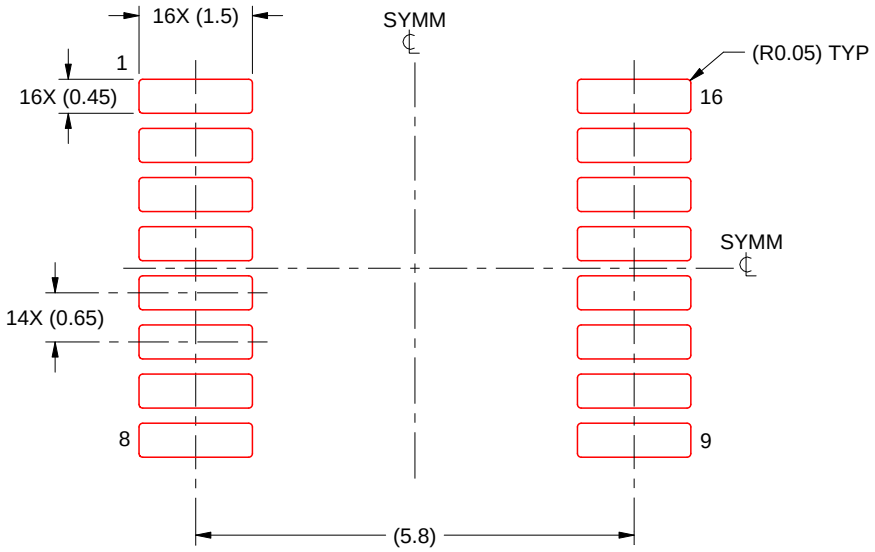
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

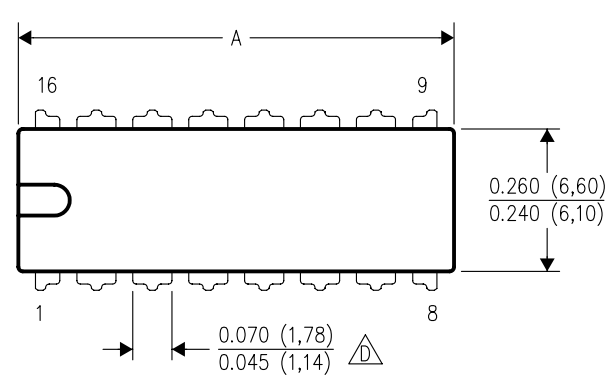
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

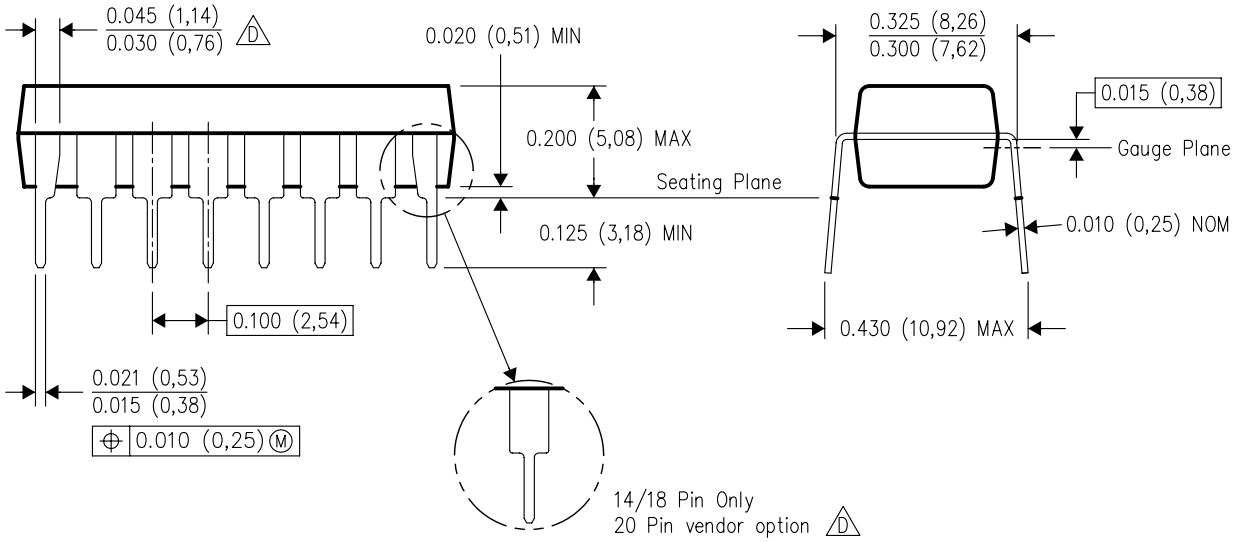
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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